Board Revision control naming convention
X.Y-Z (X= schematic ver, Y = layout version (include silk changes), Z = BOM variant)

Revision history

Changes in Rev 4.0-A
1. Add pull-ups and pull-down resistors for the serial flash
2. Move the nRESET pull from VCC_BRD to VBAT_CC
3. Add pull-up on UART_TX going to the FTDI to prevent false start bits.
4. Add pull-up resistor for Accelerometer address to avoid conflict with Audio Booster pack
5. Add 100K pull-up on RESET_OUT net for any BP without RESET pulls.
6. Change R61 to 2.7K, R57-> 270 Ohms

Rev 4.1-B

1. Changed the s-flash from Micron to Winbond
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